



Material Content Data Sheet



Sales Product Name		BSZ040N04LS G		Issued		29. August 2013		
MA#		MA000469798						
Package		PG-TSDSON-8-2		Weight*		38.76 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.836	4.74	4.74	47380	47380
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		54	
	non noble metal	zinc	7440-66-6	0.008	0.02		216	
	non noble metal	iron	7439-89-6	0.168	0.43		4326	
wire	non noble metal	copper	7440-50-8	6.808	17.56	18.02	175648	180244
	non noble metal	copper	7440-50-8	0.036	0.09	0.09	917	917
	encapsulation	organic material	carbon black	1333-86-4	0.034	0.09		868
	plastics	epoxy resin	-	1.733	4.47		44722	
	inorganic material	silicondioxide	60676-86-0	15.061	38.87	43.43	388603	434193
leadfinish	non noble metal	tin	7440-31-5	0.387	1.00	1.00	9989	9989
plating	noble metal	silver	7440-22-4	0.963	2.48	2.48	24836	24836
solder	non noble metal	tin	7440-31-5	0.037	0.10		950	
	noble metal	silver	7440-22-4	0.046	0.12		1188	
	non noble metal	lead	7439-92-1	1.759	4.54	4.76	45376	47514
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		28	
	non noble metal	zinc	7440-66-6	0.004	0.01		111	
	non noble metal	iron	7439-89-6	0.086	0.22		2225	
	non noble metal	copper	7440-50-8	3.501	9.03	9.26	90335	92699
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.002	0.00		49	
	non noble metal	zinc	7440-66-6	0.008	0.02		195	
	non noble metal	iron	7439-89-6	0.151	0.39		3893	
	non noble metal	copper	7440-50-8	6.127	15.81	16.22	158091	162228
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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